

LCFI Collaboration Status Report

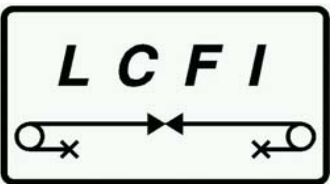
LCWS 2004

Paris

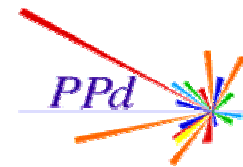
Joel Goldstein

for the LCFI Collaboration

Bristol, Lancaster, Liverpool, Oxford, RAL



LCFI Research Programme



R&D for a vertex detector at NLC or TESLA

1. Physics Studies

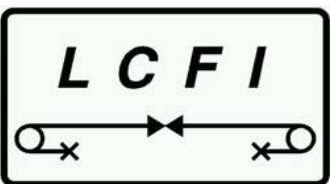
(See Sonja Hillert's talk in Simulation session)

2. Mechanical Development

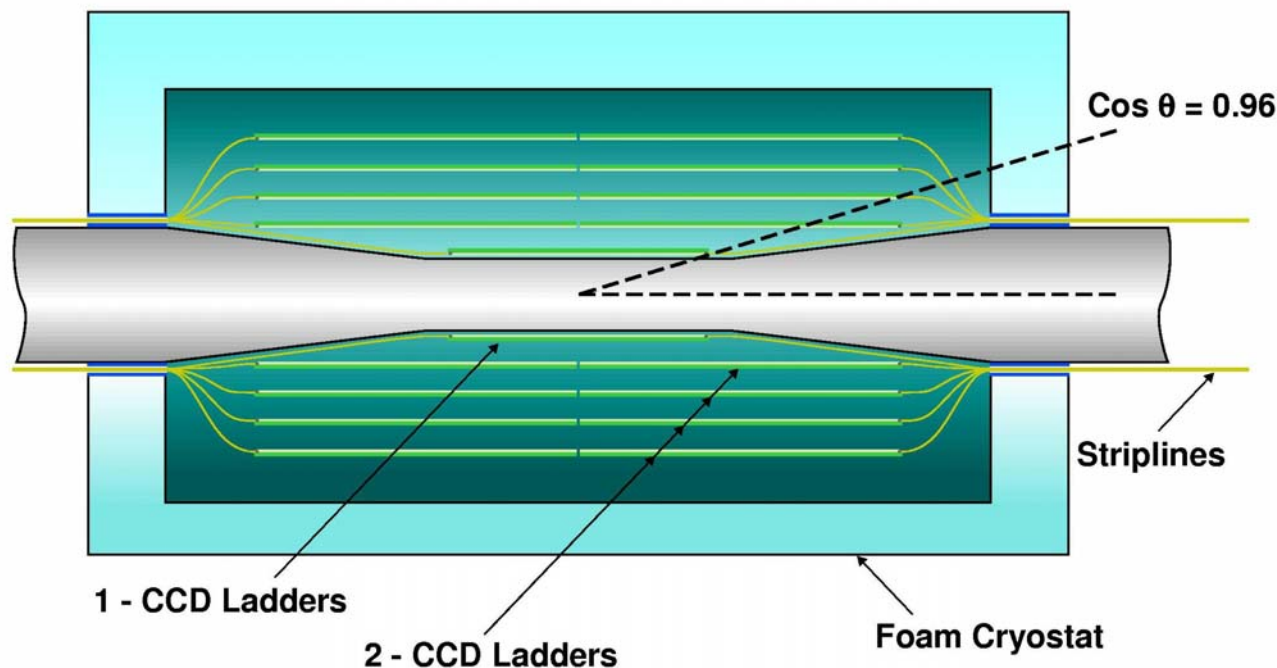
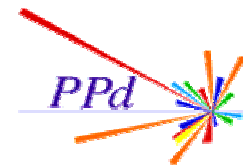
- **Ultra low-mass ladders**
- **FEA/physical models**

3. Detector Development

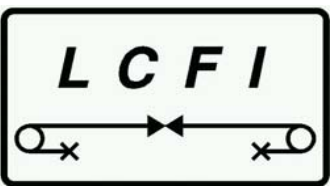
- **Fast CCD technology (50 MHz for TESLA)**
- **Custom CMOS readout chips**



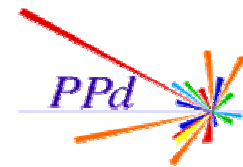
LC Vertex Detector



- 800 Mchannels of $20 \times 20 \mu\text{m}$ pixels in 5 layers
- Optimisation:
 - Inner radius (1.5 cm?)
 - Readout time ($50 \mu\text{s}$?)
 - Ladder thickness ($0.1\% X_0$?)



Mechanical Options



Target of 0.1% X_0 per layer
(100 μ m silicon equivalent)

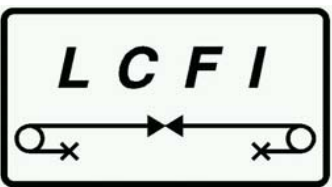
1. Unsupported Silicon

- Longitudinal tensioning provides stiffness
- No lateral stability
- Not believed to be promising

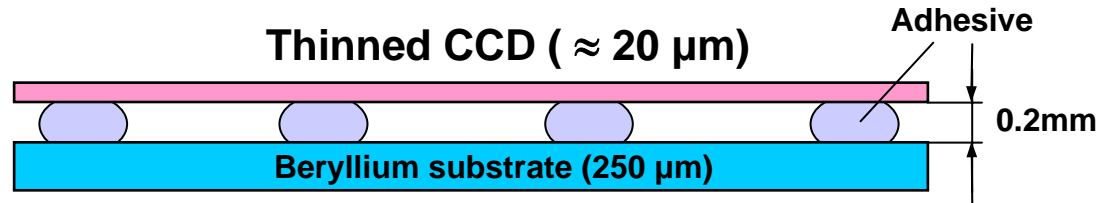
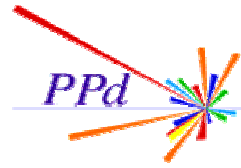
2. Semi-supported Ultra-thin Silicon

- Detector thinned to epitaxial layer (20 μ m)
- Silicon glued to low mass substrate for lateral stability
- Beryllium has best specific stiffness
- Composites, ceramics, foams...

3. Novel Structures



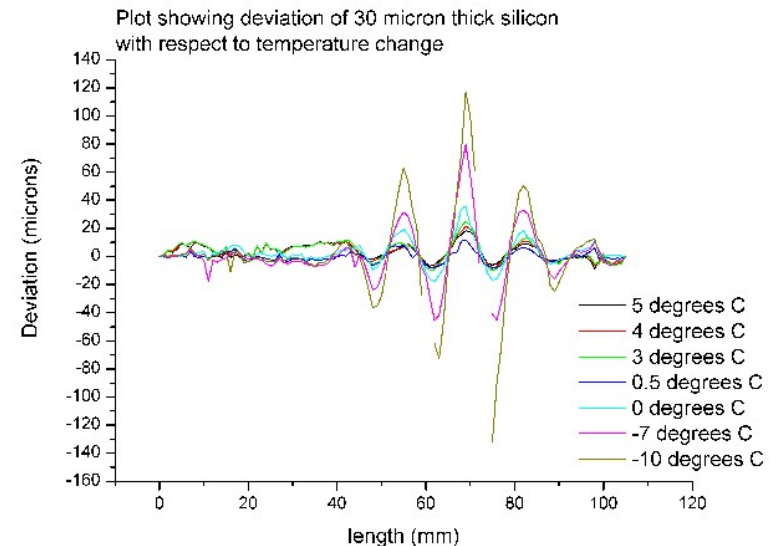
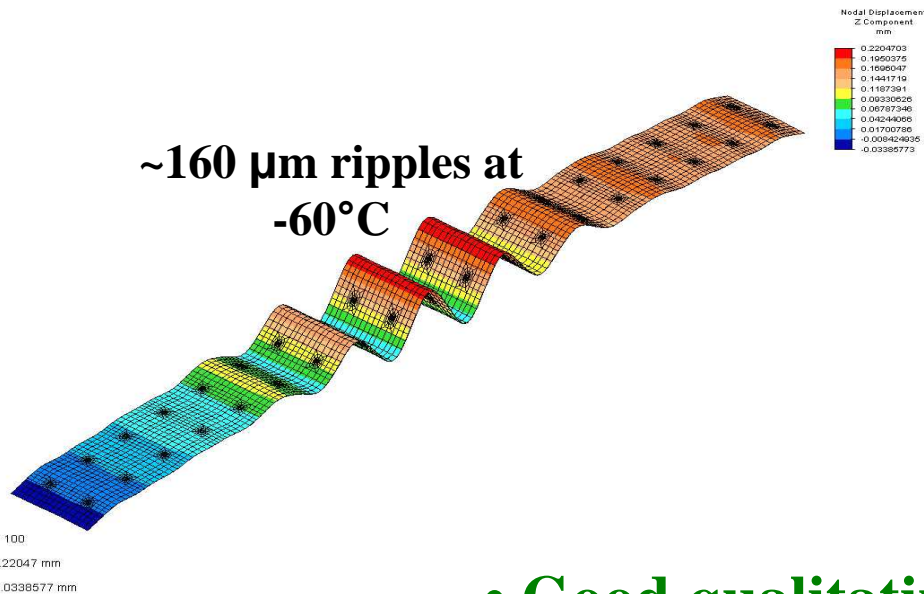
Mechanical Studies of Be-Si



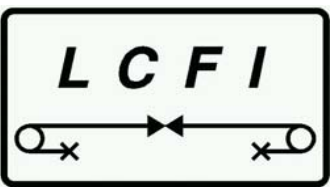
FEA Simulations

Physical Prototyping

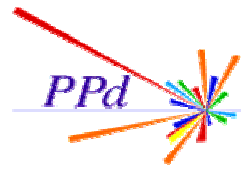
- Laser survey system**



- Good qualitative agreement**



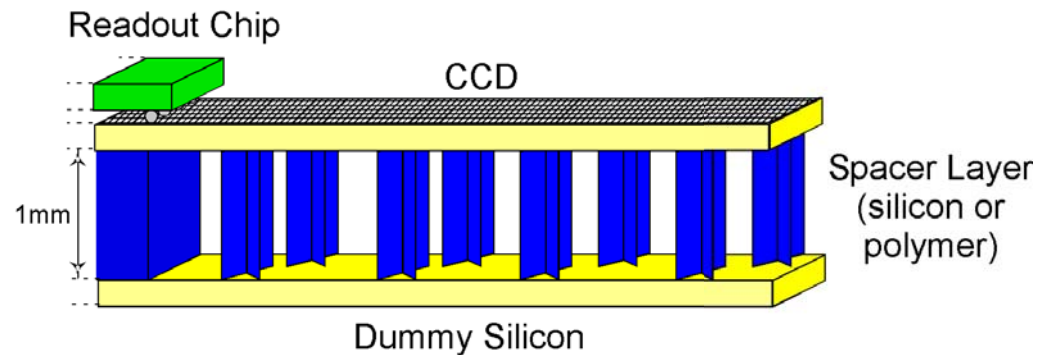
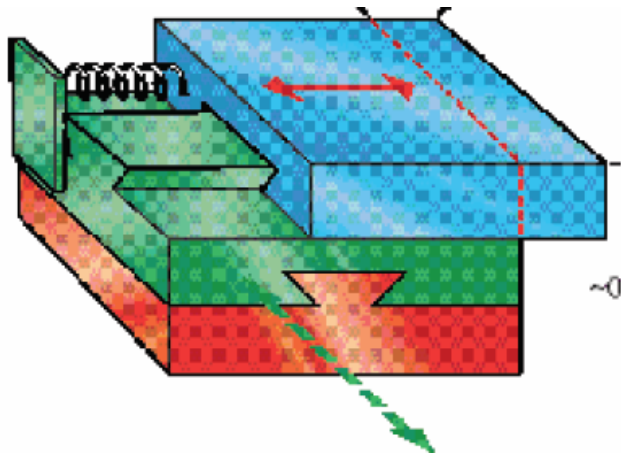
New Approaches



- Be-Si unstable when cooled due to CTE mismatch
- Choose substrate with closer CTE match
 - 100 μm carbon fibre
 - ceramic foam
- Micromechanical techniques....

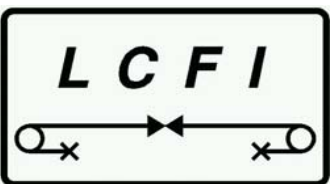
Microstages

replace glue pillars

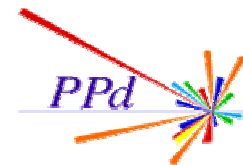


Sandwich

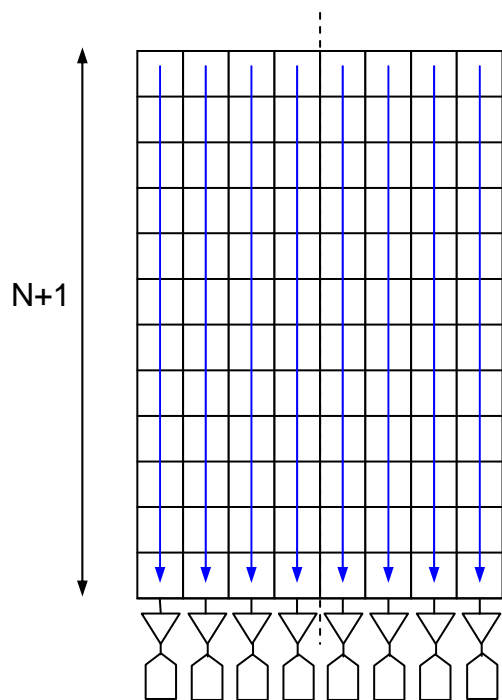
UV lithography on dummy



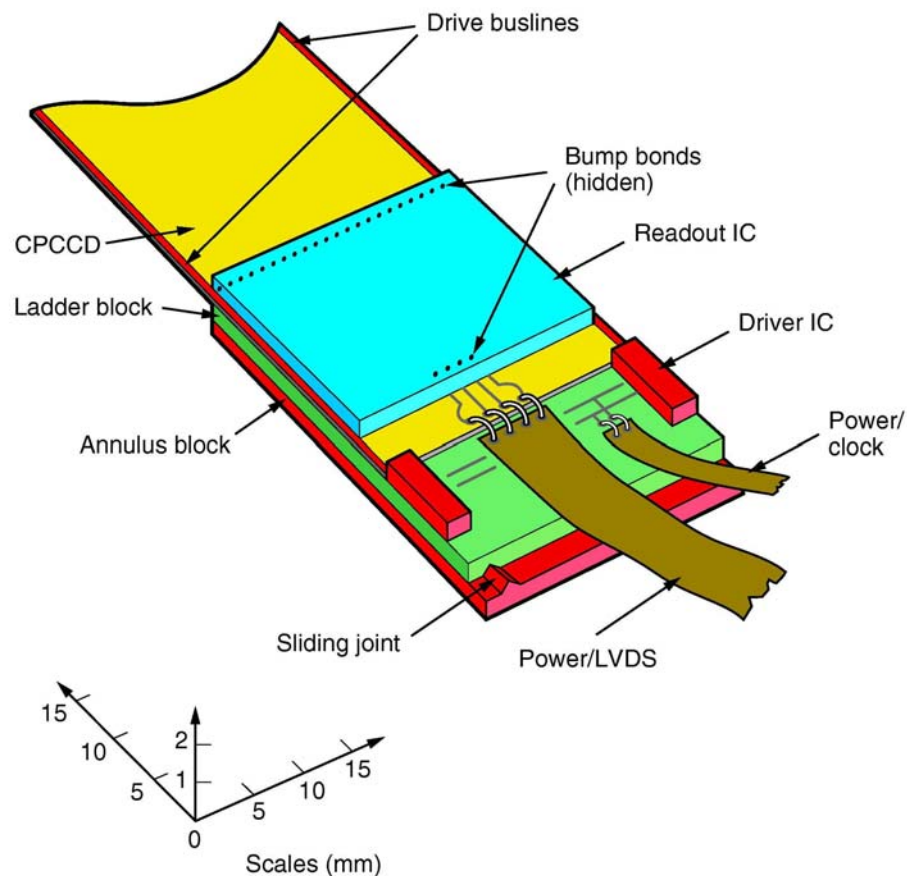
Column Parallel CCD

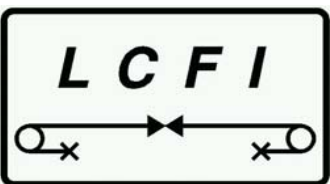


- **Separate amplifier and readout for each column**

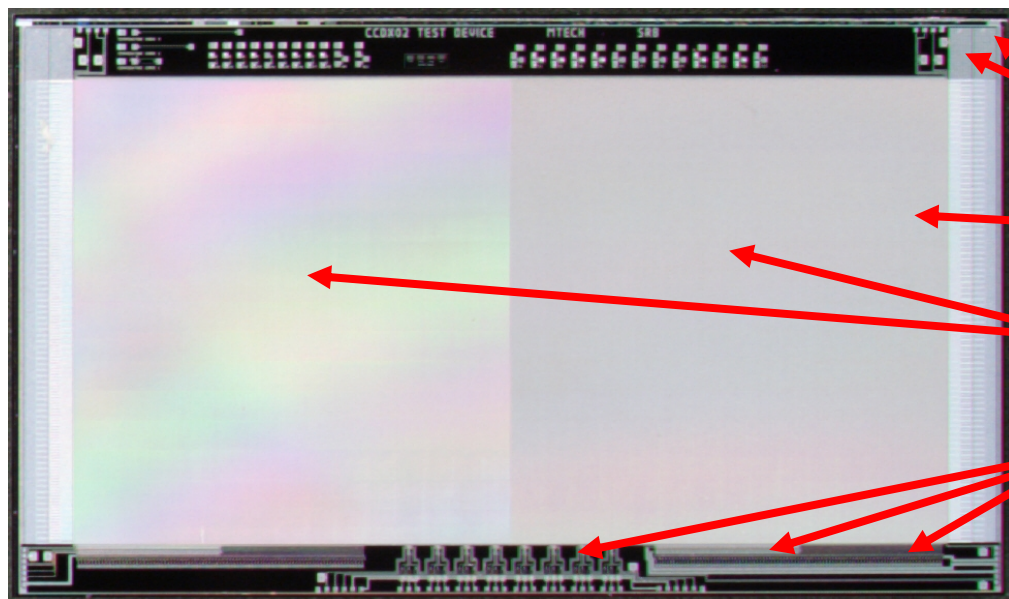
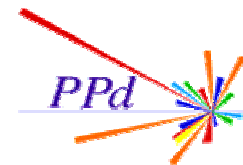


Column Parallel CCD
Readout time = $(N+1)/F_{\text{out}}$





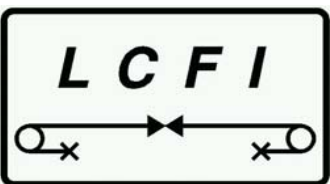
Prototype CP CCD



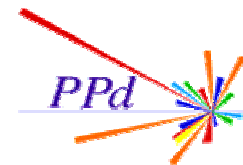
CPC1 produced by E2V

- Two phase operation
- Metal strapping for clock
- 2 different gate shapes
- 3 different types of output
- 2 different implant levels

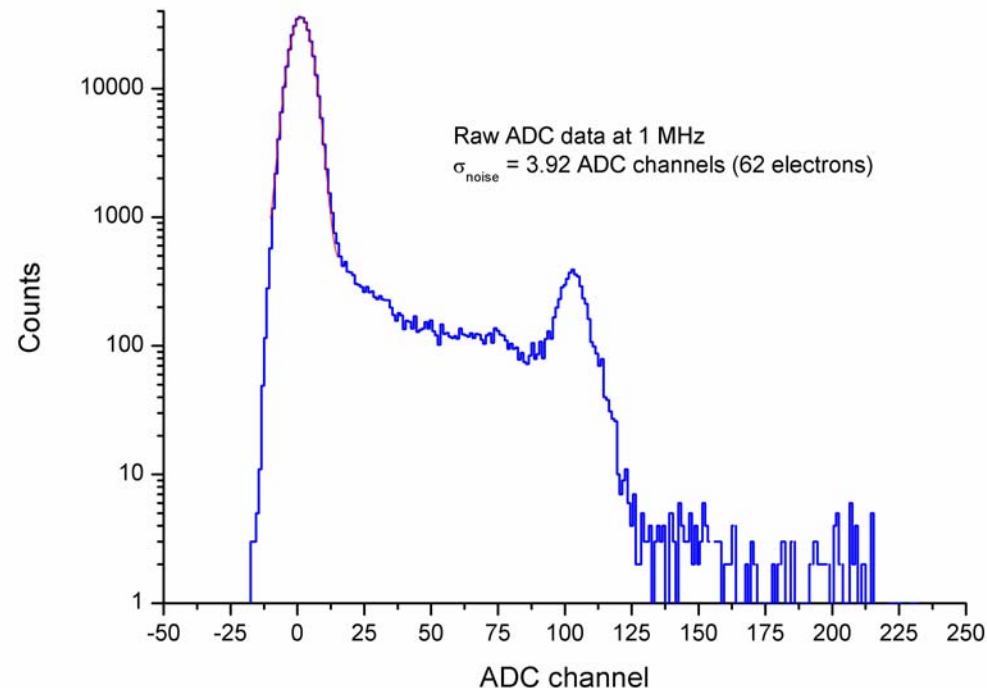
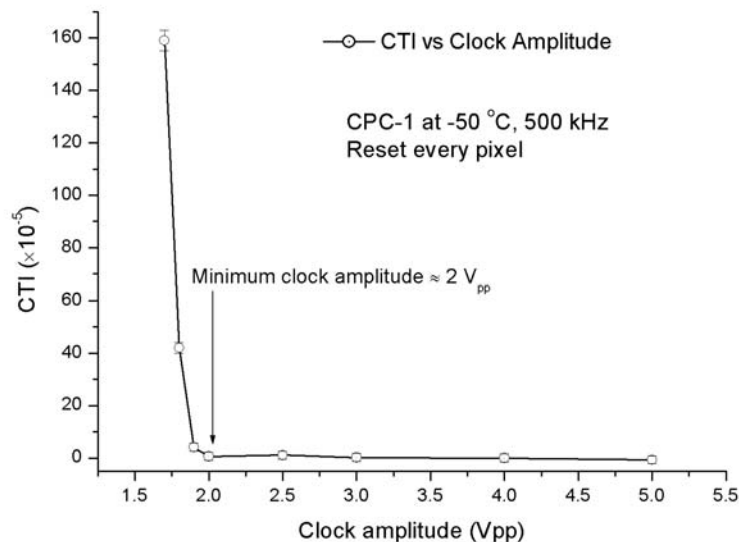
➤ *Clock with highest frequency at lowest voltage*



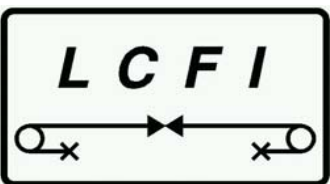
CPC1 Results



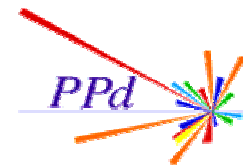
- Noise ~ 100 electrons
(60 after filter)
- Minimum clock ~1.9 V



- Maximum frequency > 25 MHz
— inherent clock asymmetry



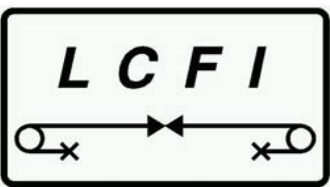
CP Readout ASIC



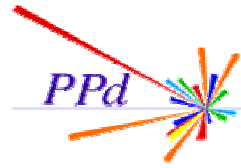
CPR1 designed by RAL ME Group

- IBM 0.25 μm process
- 250 parallel channels with 20 μm pitch
- Designed for 50 MHz
- Data multiplexed out through 2 pads

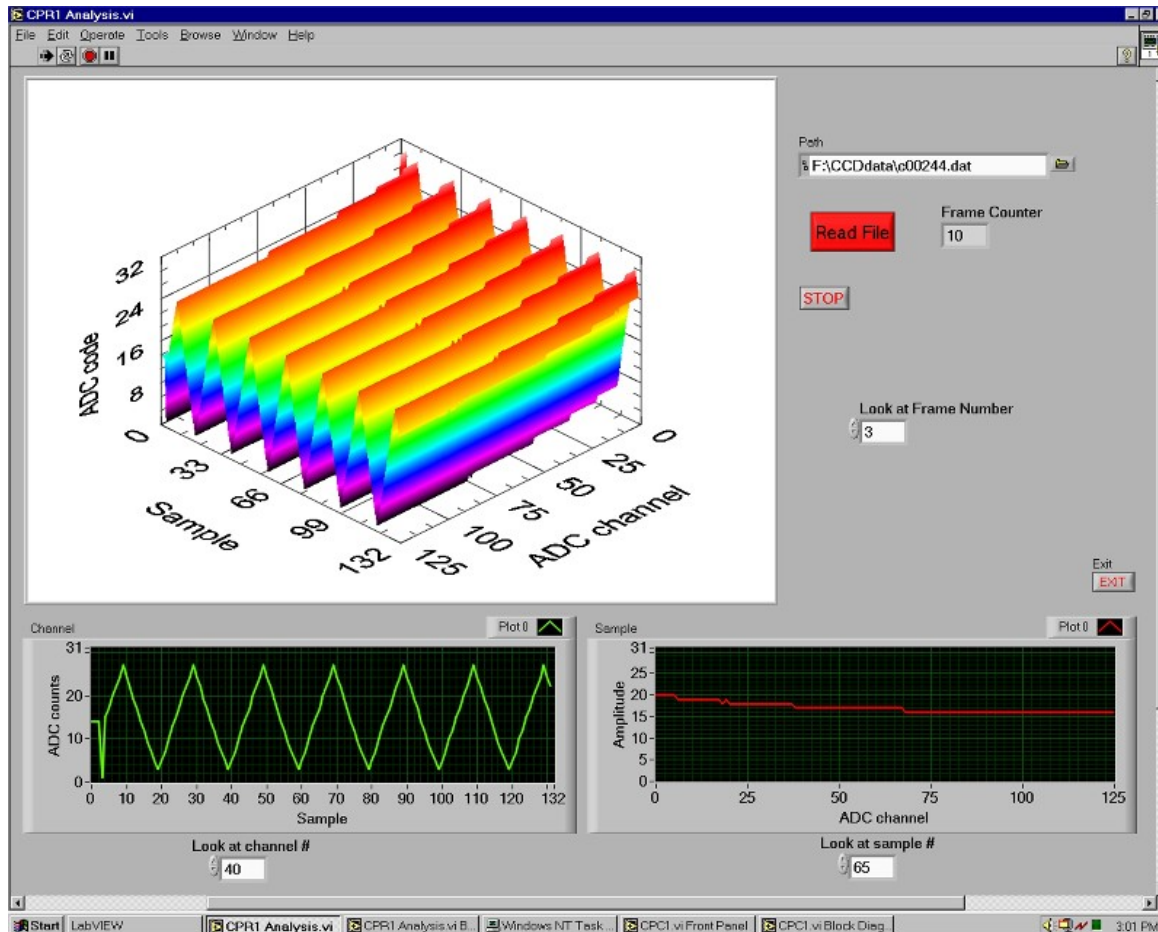




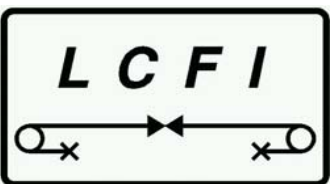
CPR1 Testing



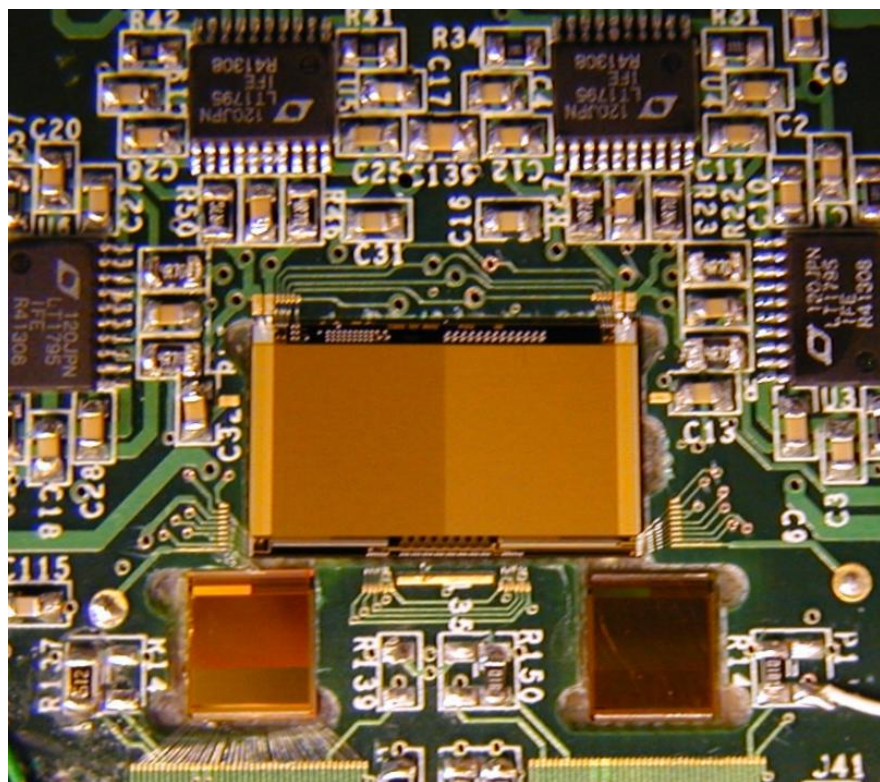
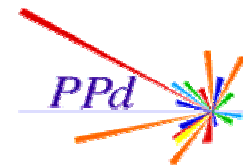
Voltage injection into ADC



- Flash ADCs tested
- Voltage and charge amplifiers tested
- Voltage gain ~40
- Very sensitive to timing and bias values
- Outstanding digital problems
- Charge amplifiers not fully understood

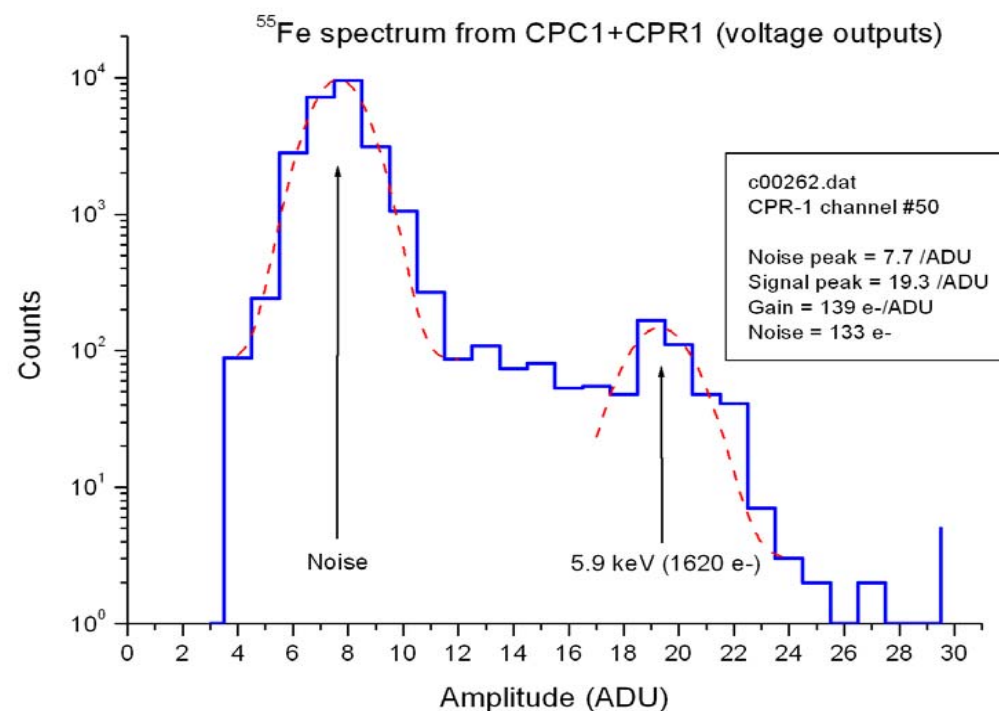


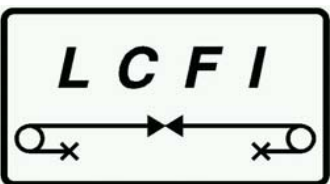
Wirebonded Assembly



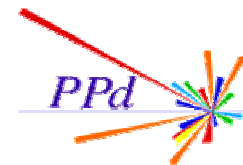
Bump bonding underway at VTT

- Total noise ~130 electrons
- Noise from preamps negligible



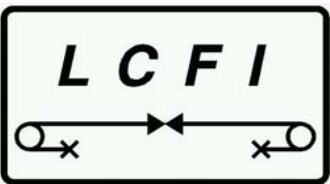


Future Detector Work

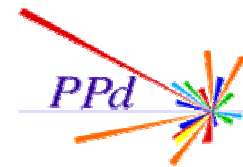


- **Test Programme**
 - Bump bonded assemblies expected early May
 - Radiation effects on fast CCDs
 - High frequency clocking
- **Next Generation CCDs and ASIC**
 - Detector scale CCDs
 - Cluster finding logic
 - Design underway; production later in year
- **In-situ Storage Devices**
 - Resistant to RF interference
 - Reduced clocking requirements

(See Chris Damerell's talk on Thursday)



Summary



- **Excellent progress over past two years**
 - **Mechanical options studied in detail**
 - **CCD+ASIC operation achieved**
 - **New ideas being discussed**
- **CP CCDs are viable technology for linear collider**
- **Next generation will be full-scale prototype CCDs**
- *Accelerator technology choice will determine path*